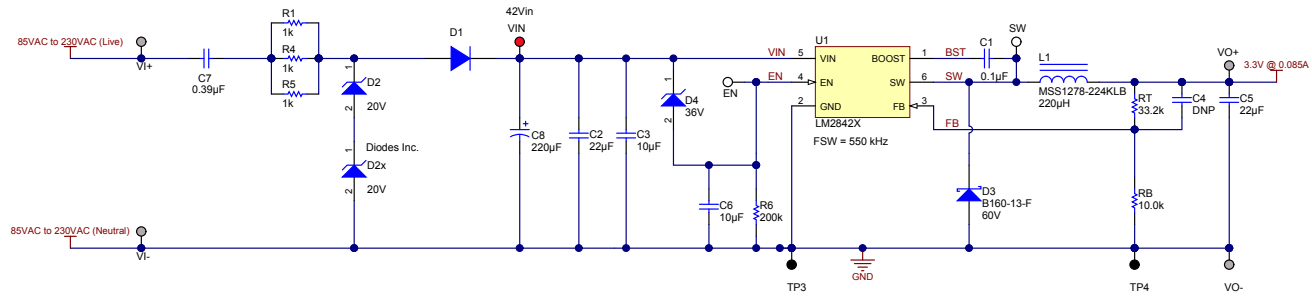


PCB  
LOGO  
DANGER HIGH VOLTAGE



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Designed for: Public Release		Mod. Date: 2/25/2014	
Project Title: Cap Drop		Sheet Title:	
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Drawn By: David Baba		File: PMP9311_REV 2_SchDoc	
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